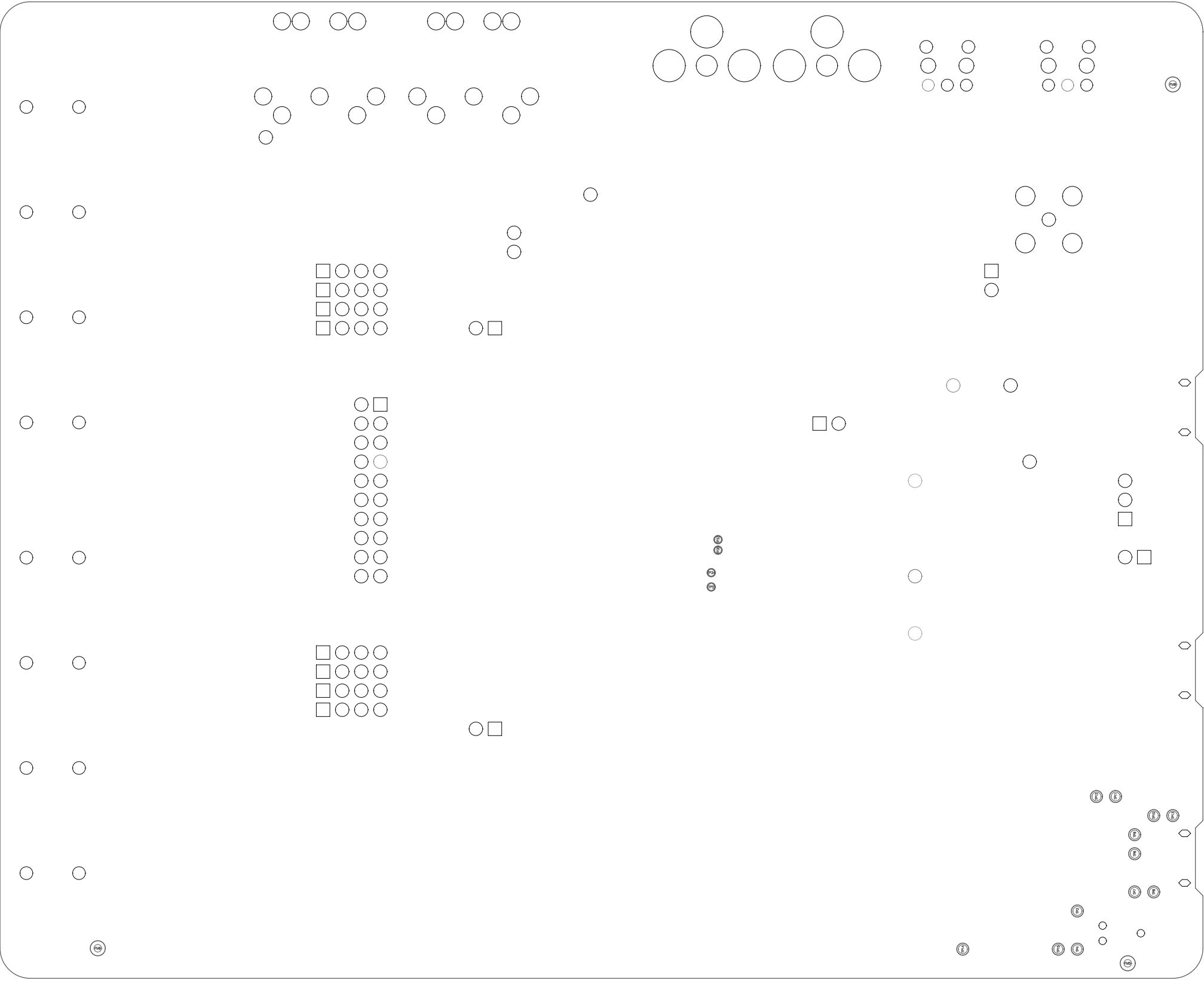


PCB ASSEMBLY INSTRUCTIONS

- 1.) SOLDERPASTE – ROHS/LEAD FREE NO CLEAN SOLDERPASTE.  
PADS HAVE NOT BEEN UNDERSIZED.  
ASSEMBLER SHOULD UNDERSIZE PADS TO SUIT PROCESS.  
SUGGEST 125UM MAX STENCIL THICKNESS.
- 2.) ENSURE THROUGH HOLE PINS OF USB CONNECTORS J23, J16 AND J2 ARE SOLDERED IN ADDITION TO SMD PADS.
- 3.) TWO PIN COMPONENT ORIENTATION:  
POLARISED MOLDED CAPACITORS – PIN 1 IS THE POLARIY MARK PIN (POSITIVE).  
MOLDED DIODES – PIN 1 IS THE POLARITY MARK PIN (CATHODE).
- 4.) NOTE USB CONNECTORS J23, J16 AND J2 HAVE A LIP THAT SITS BELOW PCB SURFACE.  
PANELUSATION SHOULD ENSURE CLEARANCE FOR THIS TO ALLOW THE CONNECTORS TO SIT FLAT.
- 5.) DO NOT EMPLOY CHEMICAL BOARD WASH OR CLEANING.

XMS0004 = 1V1 = 17 AUG 2022  
TOP ASSEMBLY



BOTTOM ASSEMBLY